



SAR10S

Aluminum Base Laminate

FEATURES

- Halogen free and High CTI
- Thermal Conductivity 1.0 W/(m·K)
- Excellent Thermal Reliability and Insulation Reliability
- MOT=140°C

APPLICATIONS

- LED TV
- Power Supply Board
- Mid-power LED Lighting

GENERAL PROPERTIES

Test Items	Test Method	Test Condition	Unit	Typical Value
Thermal Conductivity	ASTM-D5470	Dielectric layer	W/(m·K)	1.1
Thermal Resistance	ASTM-D5470	Dielectric layer	K·cm ² /W	0.91
Tg	IPC-TM-650 2.4.25D	DSC	°C	140
Td	IPC-TM-650 2.4.24.6	5% Wt. loss	°C	410
Thermal Stress	IPC-TM-650 2.4.13.1	288°C, solder float	min	30
CTE(Z-axis)	IPC-TM-650 2.4.24	Before Tg	ppm/°C	27
	IPC-TM-650 2.4.24	After Tg	ppm/°C	30
	IPC-TM-650 2.4.24	50-260°C	%	0.74
Volume Resistivity	IPC-TM-650 2.5.17.1	C-96/35/90	MΩ·cm	10 ⁶
Surface Resistivity	IPC-TM-650 2.5.17.1	C-96/35/90	MΩ	10 ⁷
Dielectric Breakdown	IPC-TM-650 2.5.6	D-48/50+D-0.5/23	kV	6
Hi-pot Test	GB/T 31988	DC	V	4000
		AC	V	3000
Peel Strength(1oz)	IPC-TM-650 2.4.8	288°C/10s	N/mm	1.4
Flammability	UL94	C-48/23/50	Rating	V-0
CTI	IEC60112	A	Rating	PLC 0

Remarks: Typical value is based on specimen of 1.5mm Al/100μm dielectric/1oz Cu.

All the typical values listed above are for your reference only and not intended for specification. Please contact Shengyi Technology Co., Ltd. for detailed information. All rights from this data sheet are reserved by Shengyi Technology Co., Ltd.

Explanation: C=Humidity conditioning, D=Immersion conditioning in distilled water, E=Temperature conditioning

PURCHASING INFORMATION

Item	Material	Thickness
Cu	E/D Cu	Hoz-6oz
Dielectric Layer	Epoxy resin filled with inorganic filler	50-150μm
Aluminum Plate	1060、5052Al	0.3-3.0mm
Protective Film	PET	50/60um
Standard Size	1040mm×1240, 510mm×610mm (Other sizes are available upon request)	